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**1 The assessment of the degree of paper aging and remaining life of filled paper-insulated high voltage underground transmission cables through wet-tensile strength**

*Singh, N.; Morel, O.E.; Singh, S.K.; Rodenbaugh, T.J.;*

Electrical Electronics Insulation Conference, 1995, and Electrical Manufacturing Coil Winding Conference. Proceedings, 18-21 Sept. 1995

Pages:443 - 447

[\[Abstract\]](#)[\[PDF Full-Text \(376 KB\)\]](#)**IEEE CNF**

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